

# Advance Product Change Notification

Issue Date: 23-Feb-2019

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# 201902020A



# **Management Summary**

ON8077 & TFF1044 change of industrial flow from Amkor Taiwan and Amkor Philippines to Amkor Korea.

Change Category

[] Wafer Fab Process	[] Assembly	[X] Product Marking	[] Test Location	[] Design
	Process			
[] Wafer Fab Materials	[X]	[] Mechanical	[]Test	[] Errata
	Assembly	Specification	Process	
	Materials	•		
[] Wafer Fab Location	[X]	[]	[] Test	[] Electrical
	Assembly	Packing/Shipping/Labeling	Equipment	
	Location			coverage
[] Firmware	[] Other			· ·

ON8077 & TFF1044: Bumping/Assembly Transfer from Amkor

Taiwan/Philippines to Amkor

Korea.

# **Description of Change**

Change of industrial flow from Amkor Taiwan and Amkor Philippines to Amkor Korea. In the current flow wafer bumping is done by ATT5 (Taiwan) and assembly is done by ATP3 (Philippines), in the new flow both bumping and assembly will be done by ATK4 (Korea).

To be aligned with Amkor Korea assembly process, during this transfer a standard released ATK4 molding compound will be qualified for the product as this compound is a new material for these products. The current ATP3 compound is Hitachi GE100RFC32, the new ATK4 compound is Sumitomo G355. **Reason for Change** 

Discontinuation of FC-CSP assembly at ATP3 and simplify supply chain to have both (bumping/assembly) in one location.

#### **Identification of Affected Products**

Top side marking

# **Product Availability**

### **Sample Information**

Samples are available from 15-Mar-2019

#### **Production**

Planned first shipment 21-Jun-2019

# Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

#### **Data Sheet Revision**

A new datasheet will be issued

## **Disposition of Old Products**

Existing inventory will be shipped until depleted

#### Timing and Logistics

The Self Qualification Report will be ready on 22-Mar-2019.

The Final PCN is planned to be issued on: 22-Mar-2019.

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 25-Mar-2019.

## **Contact and Support**

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

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Customer Focus, Passion to Win.

### NXP Quality Management Team.

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